

General Description

The Sanrise SRC65R040B is a high voltage power MOSFET, fabricated using advanced super junction technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density and outstanding efficiency.

The SRC65R040B break down voltage is 650V and it has a high rugged avalanche characteristics. The SRC65R040B is available in TO-247 package.

Features

- Ultra Low $R_{DS(ON)} = 40m\Omega @ V_{GS} = 10V$.
- Ultra Low Gate Charge, $Q_g = 210nC$ typ.
- Fast switching capability
- Robust design with better EAS performance
- EMI Improved
- Non-automotive Qualified

Symbol

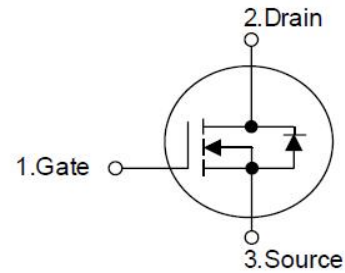
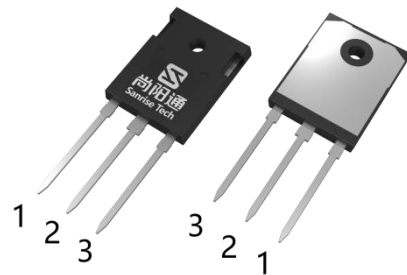


Figure 1 Symbol of SRC65R040B

Package Type



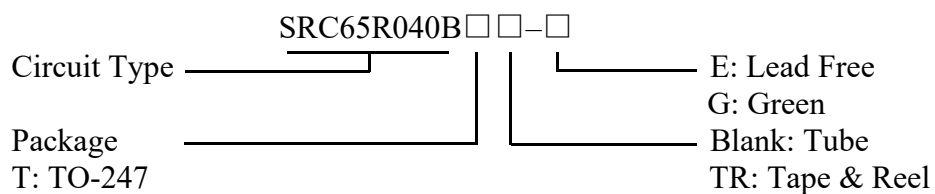
TO-247

Figure 2 Package Type of SRC65R040B

Application

- Telecom Power
- EV Charger

Ordering Information



Package	Part Number		Marking ID		Packing Type
	Lead Free	Green	Lead Free	Green	
TO-247	SRC65R040BT-E	SRC65R040BT-G	SRC65R040BTE	SRC65R040BTG	Tube

Absolute Maximum Ratings^{Note 1}

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V_{DSS}	650	V
Drain-Source Voltage($T_j=150^{\circ}\text{C}$)		V_{DSS}	700	V
Gate-Source Voltage (static)		V_{GSS}	± 20	V
Gate-Source Voltage (dynamic), AC ($f>1\text{ Hz}$)		V_{GSS}	± 30	V
Power Dissipation($T_c=25^{\circ}\text{C}, T_O=247$)		P_{tot}	568	W
Continuous Drain Current	$T_c=25^{\circ}\text{C}$	I_D	77	A
	$T_c=100^{\circ}\text{C}$		48	
	$T_c=125^{\circ}\text{C}$		34	
Pulsed Drain Current (Note 2)		I_{DM}	231	A
Avalanche Energy, Single Pulse (Note 3)		E_{AS}	264	mJ
Avalanche Energy, Repetitive (Note 2)		E_{AR}	0.264	mJ
Avalanche Current, Repetitive (Note 2)		I_{AR}	2.8	A
Continuous Diode Forward Current		I_S	77	A
Diode Pulse Current		$I_{S,PULSE}$	231	A
Maximum diode commutation speed(Note 4)		di_F/dt	900	A/us
MOSFET dv/dt Ruggedness, $V_{DS}\leq 480\text{V}$		dv/dt	80	V/ns
Reverse Diode dv/dt , $V_{DS}\leq 480\text{V}, I_{SD}\leq I_D$		dv/dt	50	V/ns
Operating Junction Temperature		T_J	150	$^{\circ}\text{C}$
Storage Temperature		T_{STG}	-55 to 150	$^{\circ}\text{C}$
Lead Temperature (Soldering, 10 sec)		T_{LEAD}	260	$^{\circ}\text{C}$

Note:

- Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
- Repetitive Rating: Pulse width limited by maximum junction temperature
- $I_{AS}=2.8\text{A}$, $V_{DD}=60\text{V}$, $R_G=25\Omega$, Starting $T_J=25^{\circ}\text{C}$
- $V_{DS}=0\text{...}400\text{V}$, $I_{SD}\leq 34\text{A}$, $T_j=25^{\circ}\text{C}$

Thermal characteristics

Parameter (TO247-package)	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Case	R_{thJC}	-		0.22	$^{\circ}\text{C/W}$
Thermal Resistance, Junction-to-Ambient	R_{thJA}	-		62	

Electrical Characteristics

$T_j = 25^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	650			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=650V, V_{GS}=0V$			20	μA
Gate-Body Leakage Current	Forward	$I_{GSSF}, V_{GS}=20V, V_{DS}=0V$			100	nA
	Reverse	$I_{GSSR}, V_{GS}=-20V, V_{DS}=0V$			-100	
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=1.85mA$	3.5	4.3	5.0	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=34A$		35	40	$m\Omega$
Gate Resistance	R_G	$f=1MHz, \text{Open Drain}$		2.0		Ω
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=25V, V_{GS}=0V, f=1MHz$		4.9		nF
Output Capacitance	C_{OSS}			4.8		nF
Reverse Transfer Capacitance	C_{RSS}			341		pF
Effective output capacitance, energy related ^{NOTE5}	$C_{O(er)}$	$V_{GS}=0V, V_{DS}=0\dots 480V$		185		pF
Effective output capacitance, time related ^{NOTE6}	$C_{O(tr)}$			1264		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=400V, I_D=34A, R_G=3.3\Omega, V_{GS}=10V$		14		ns
Rise Time	t_r			8		
Turn-off Delay Time	$t_{d(off)}$			102		
Fall Time	t_f			6.1		
Gate Charge Characteristics						
Gate to Source Charge	Q_{gs}	$V_{DD}=480V, I_D=34A, V_{GS}=0 \text{ to } 10V$		31.7		nC
Gate to Drain Charge	Q_{gd}			104		
Gate Charge Total	Q_g			210		
Gate Plateau Voltage	$V_{plateau}$			6.3		V
Reverse Diode Characteristics						
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_{SD}=34A$		0.86	1.1	V
Reverse Recovery Time	t_{rr}	$V_R=400V, I_F=34A, dI_F/dt=100A/us$		176		ns
Reverse Recovery Charge	Q_{rr}			1.28		μC
Peak Reverse Recovery Current	I_{rrm}			14.5		A

Note:

- $C_{O(er)}$ is a fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0 to 480V
- $C_{O(tr)}$ is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 480V

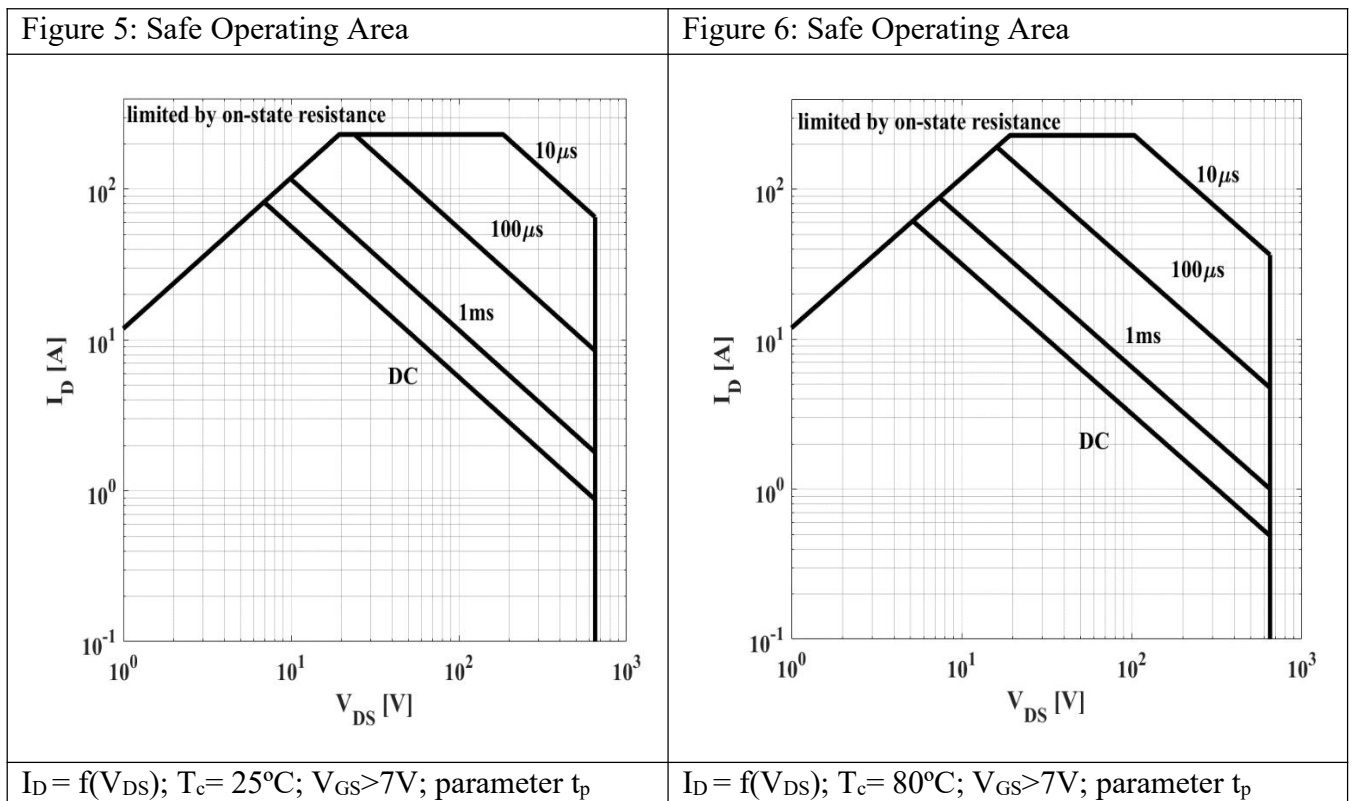
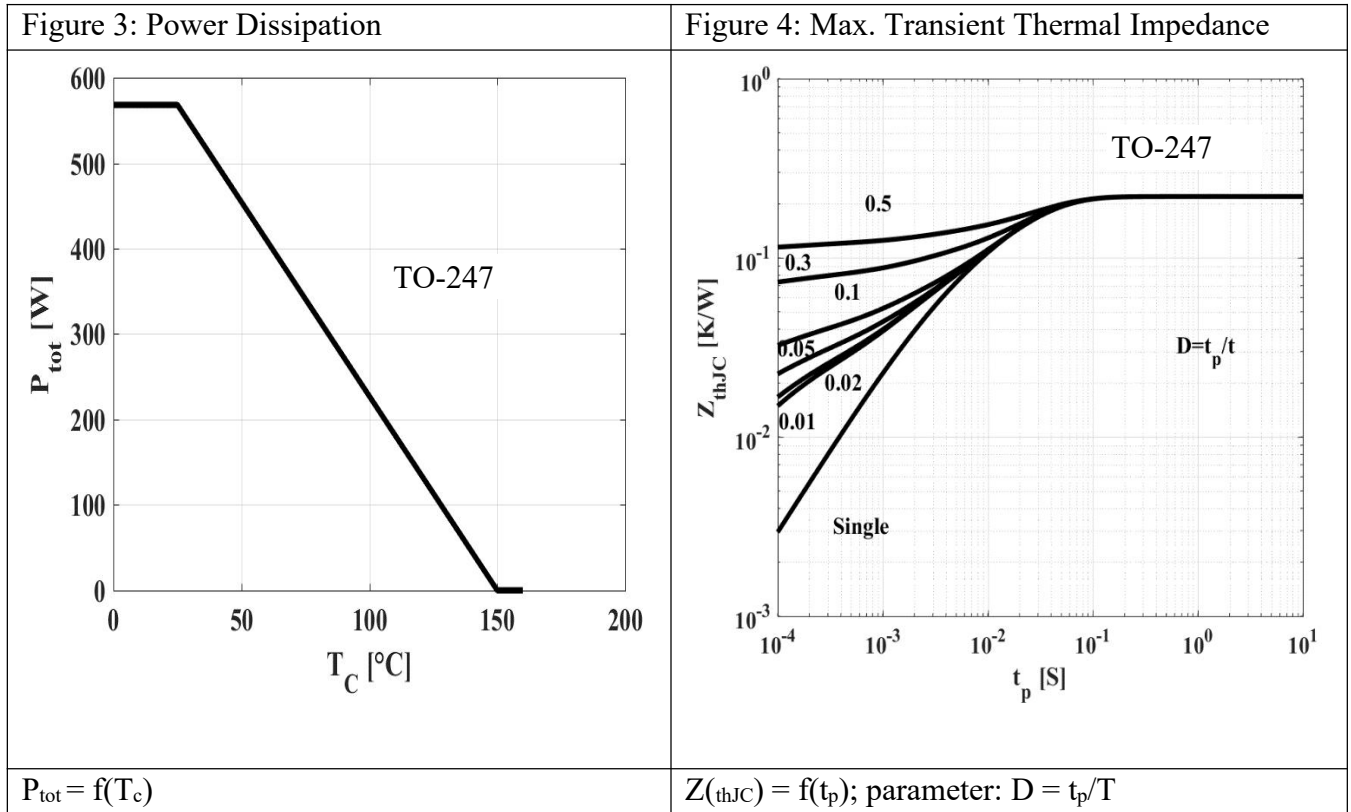
Typical Performance Characteristics


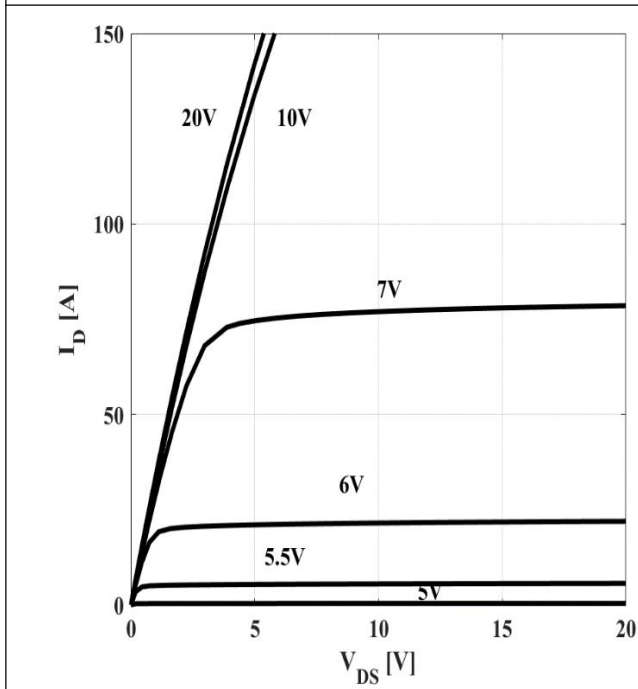
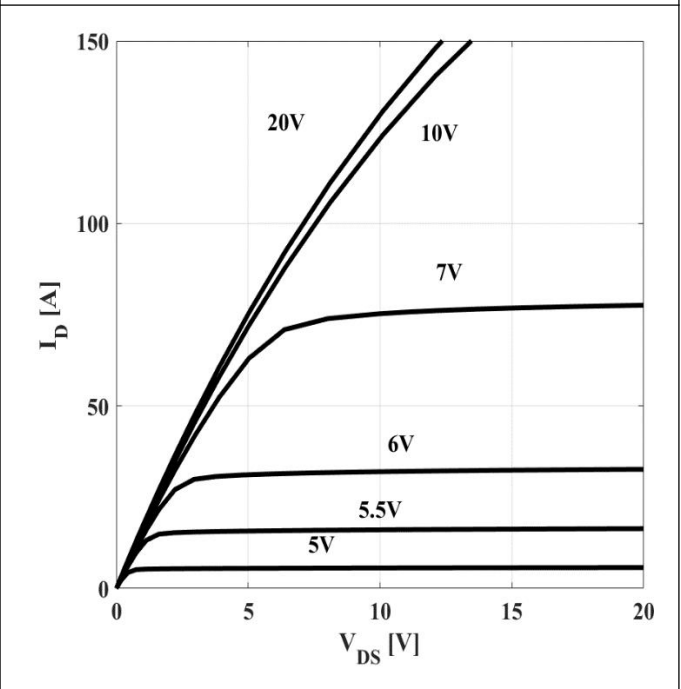
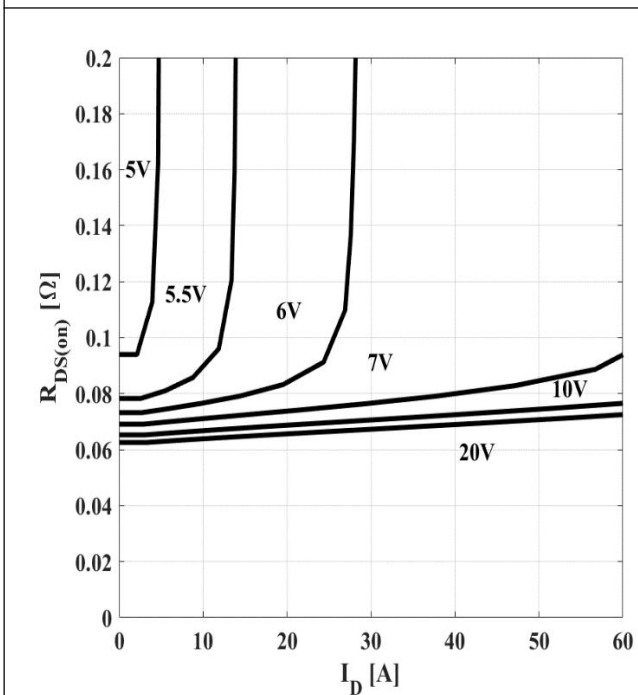
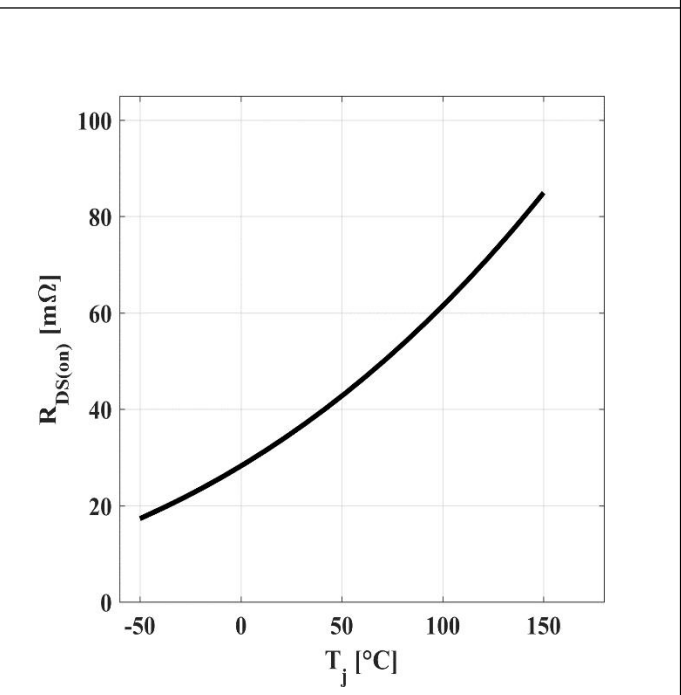
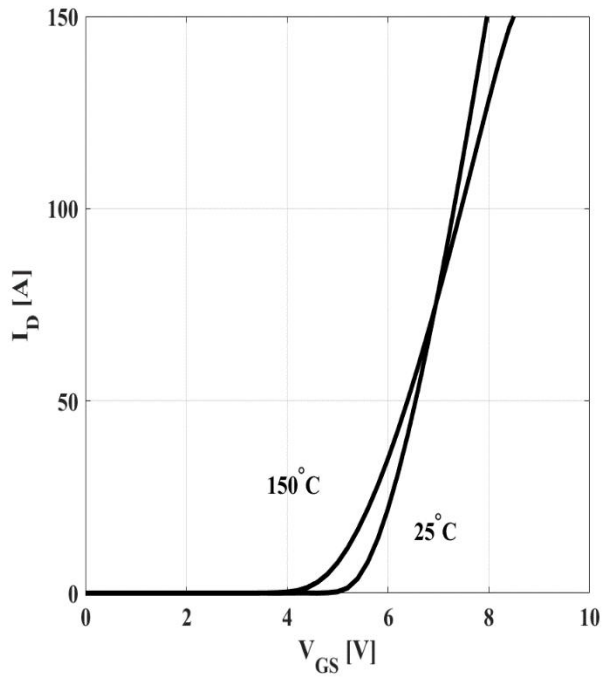
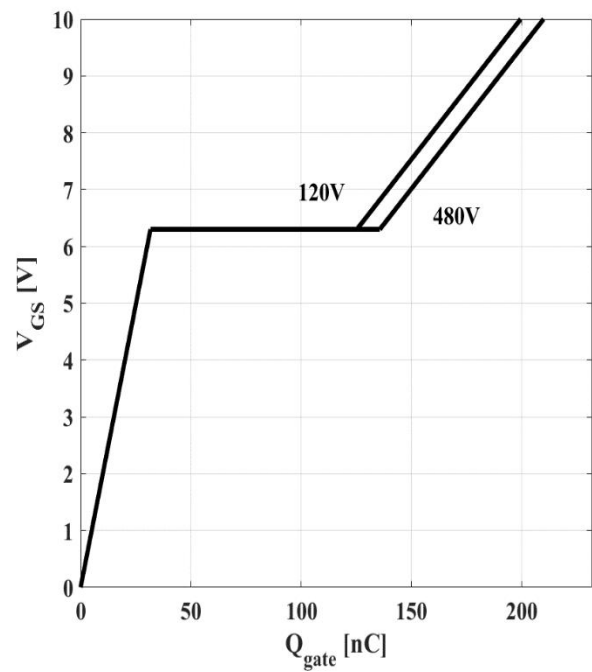
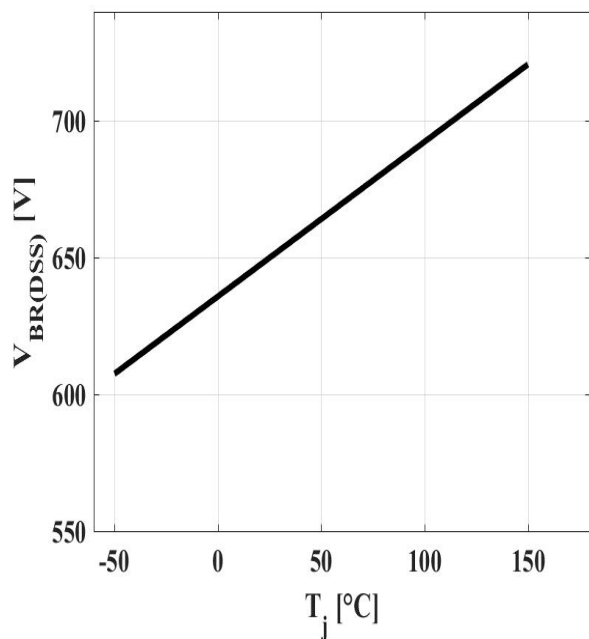
Figure 7: Typ. Output Characteristics

 $I_D = f(V_{DS}); T_j = 25^\circ\text{C}; \text{parameter: } V_{GS}$
Figure 8: Typ. Output Characteristics

 $I_D = f(V_{DS}); T_j = 125^\circ\text{C}; \text{parameter: } V_{GS}$
Figure 9: Typ. Drain-Source On-State Resistance

 $R_{DS(ON)} = f(I_D); T_j = 125^\circ\text{C}; \text{parameter: } V_{GS}$
Figure 10: Typ. Drain-Source On-State Resistance

 $R_{DS(ON)} = f(T_j); I_D = 34\text{A}; V_{GS} = 10\text{V}$

Figure 11: Typ. Transfer Characteristics


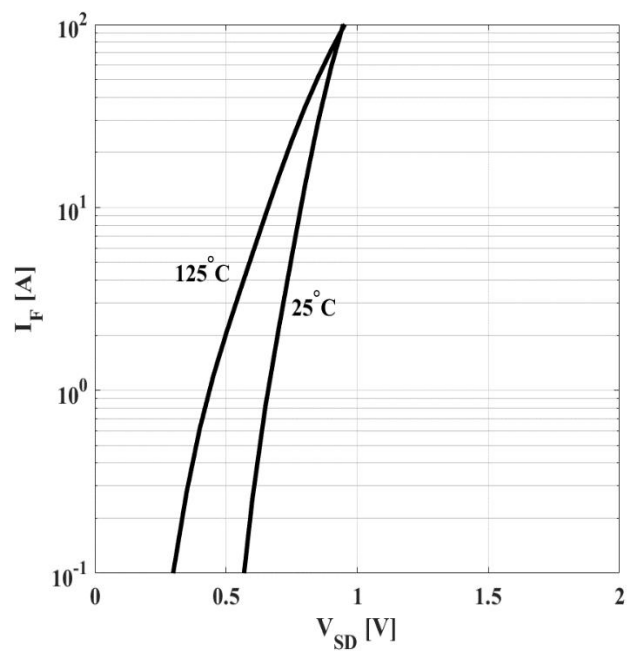
$$I_D = f(V_{GS}); V_{DS} = 20\text{V}$$

Figure 12: Typ. Gate Charge


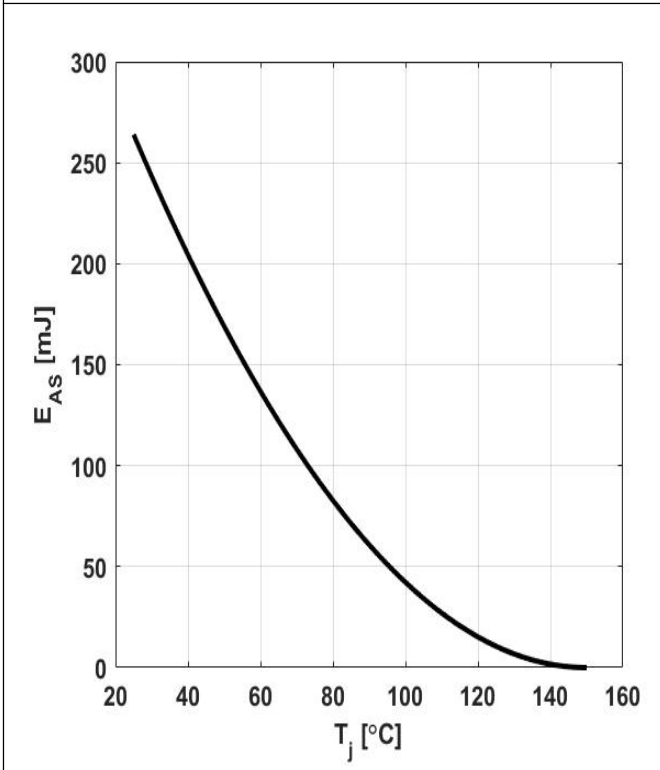
$$V_{GS} = f(Q_{gate}), I_D = 34\text{A pulsed}$$

Figure 13: Drain-Source Breakdown Voltage


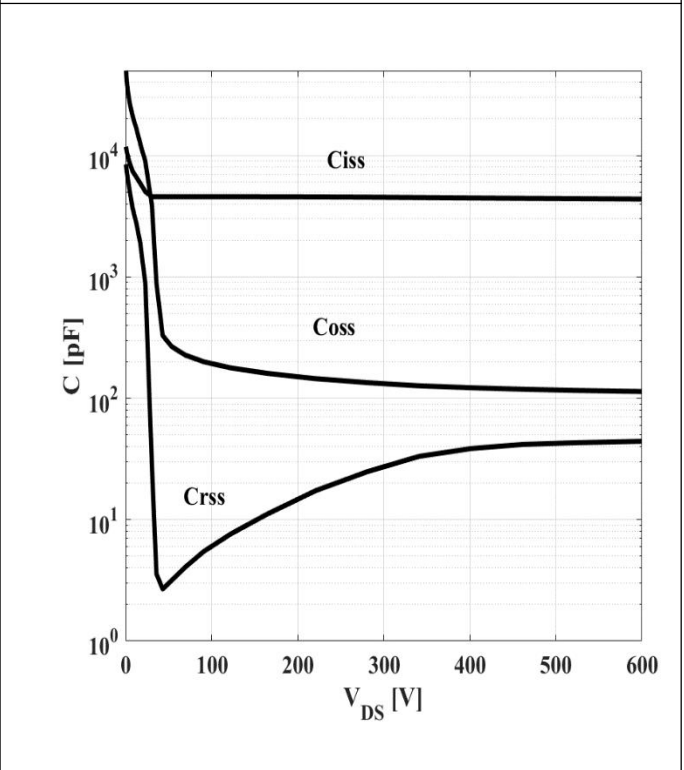
$$V_{BR(DSS)} = f(T_j); I_D = 10\text{mA}$$

Figure 14: Forward Characteristics of Reverse Diode


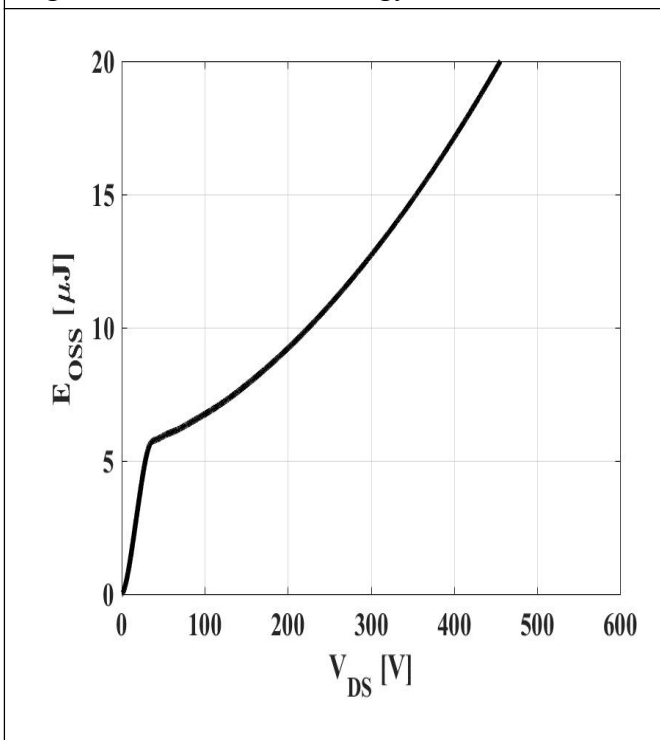
$$I_F = f(V_{SD}); \text{parameter: } T_j$$

Figure 15: Avalanche Energy


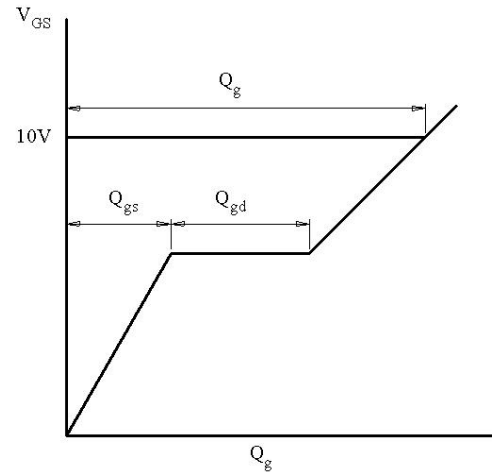
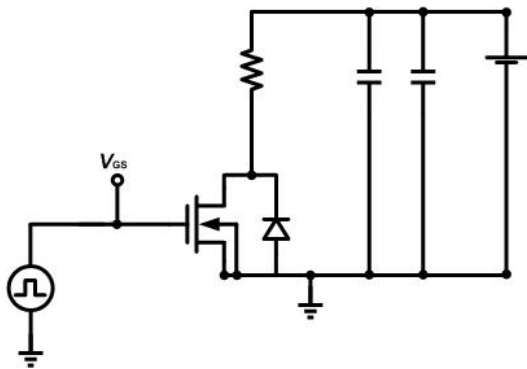
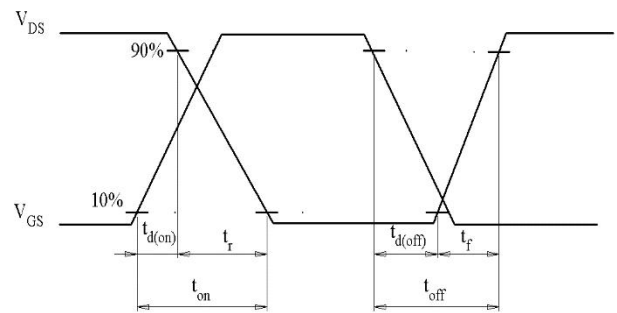
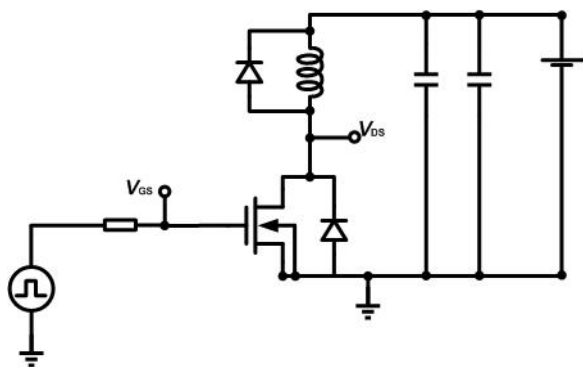
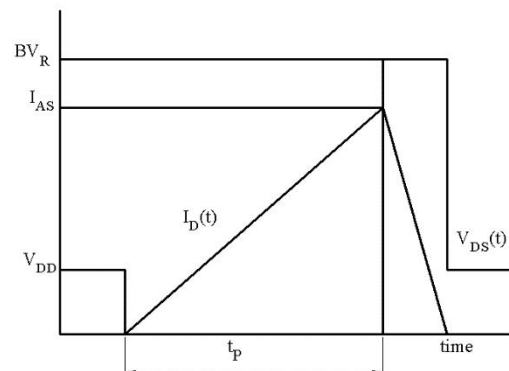
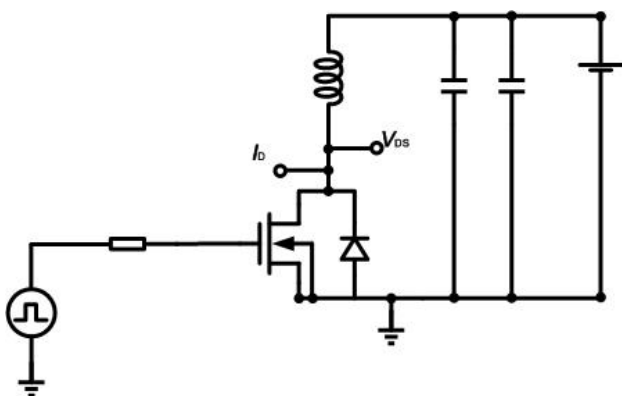
$$E_{AS}=f(T_j); I_D=2.8A; V_{DD}=60V$$

Figure 16: Typ. Capacitances


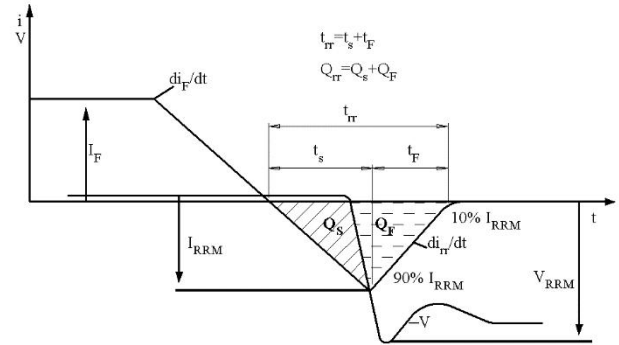
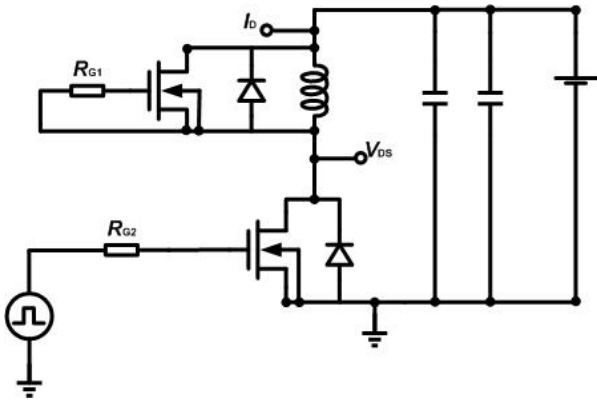
$$C=f(V_{DS}); V_{GS}=0; f=1MHz$$

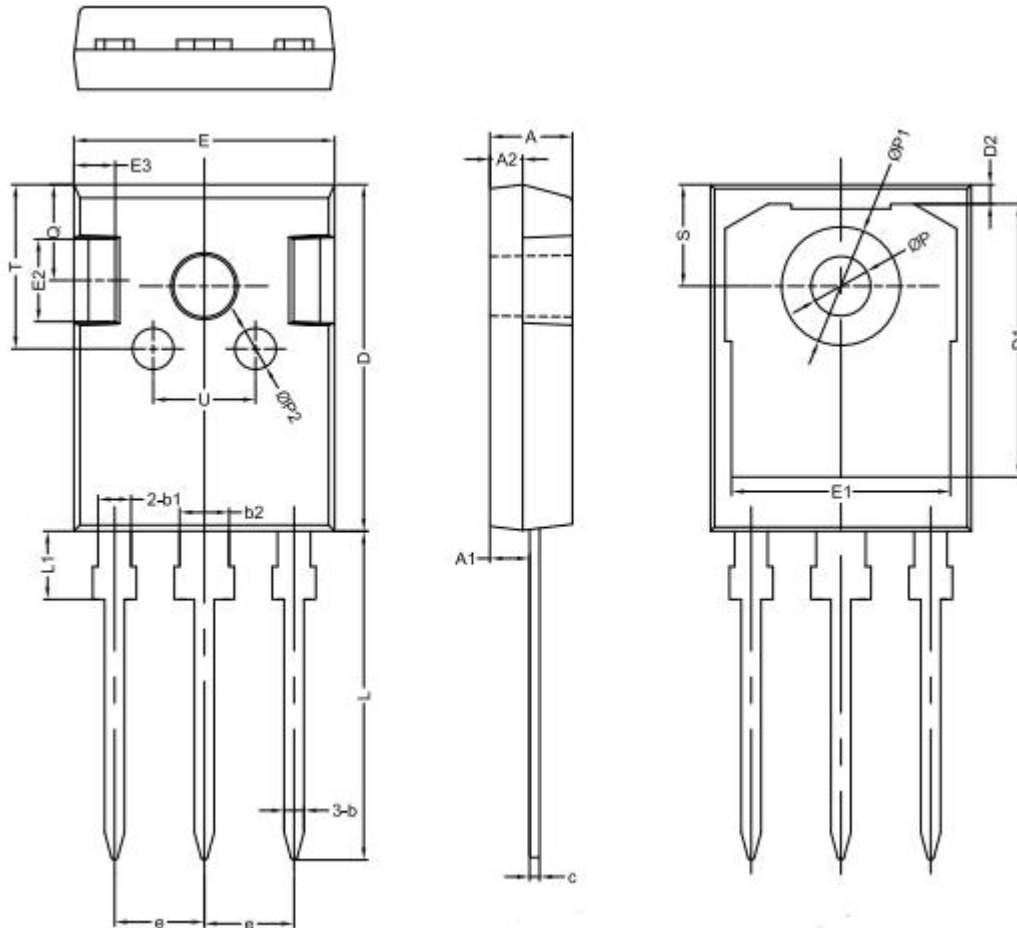
Figure 17: Coss Stored Energy


$$E_{OSS}=f(V_{DS})$$

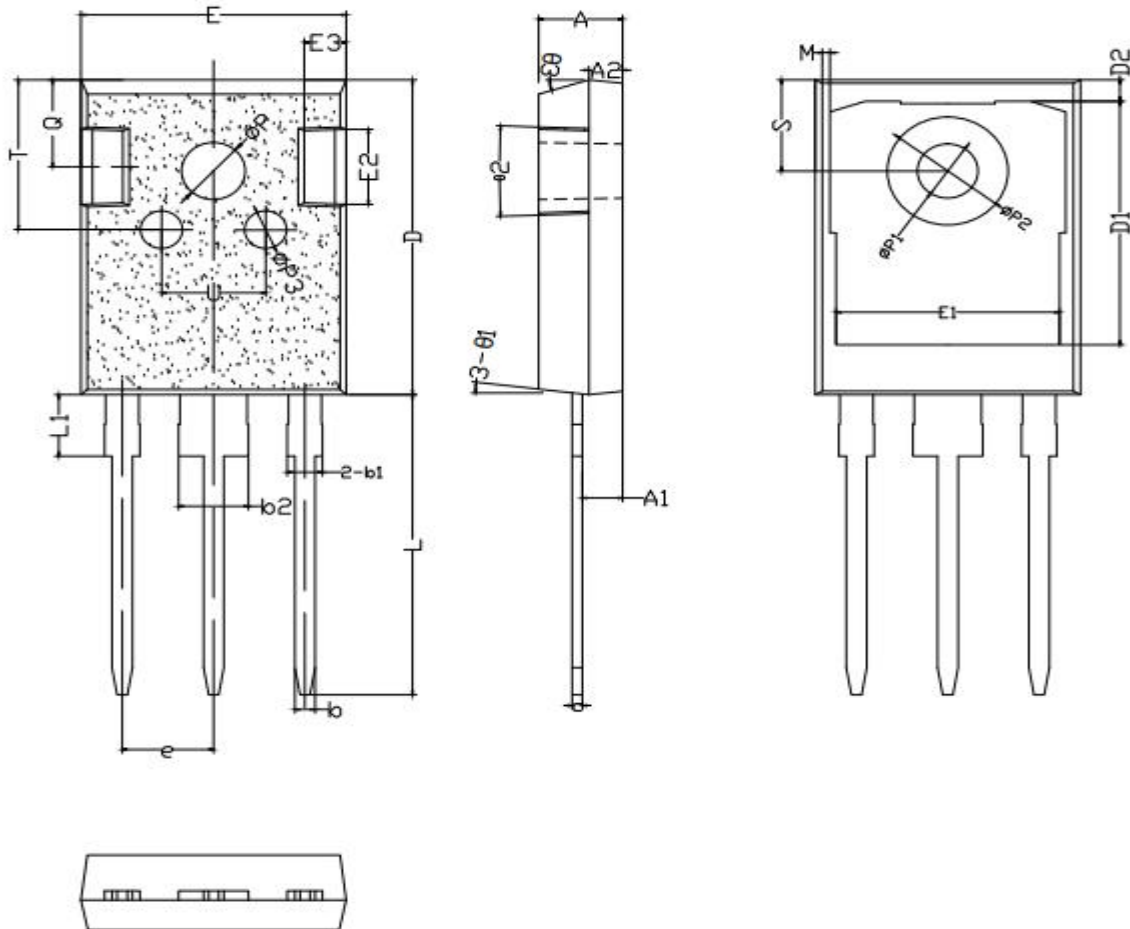
Test Circuits
1. Gate Charge Test Circuit & Waveform

2. Switch Time Test Circuit

3. Unclaimed Inductive Switching Test Circuit & Waveforms


4. Test Circuit and Waveform for Diode Characteristics

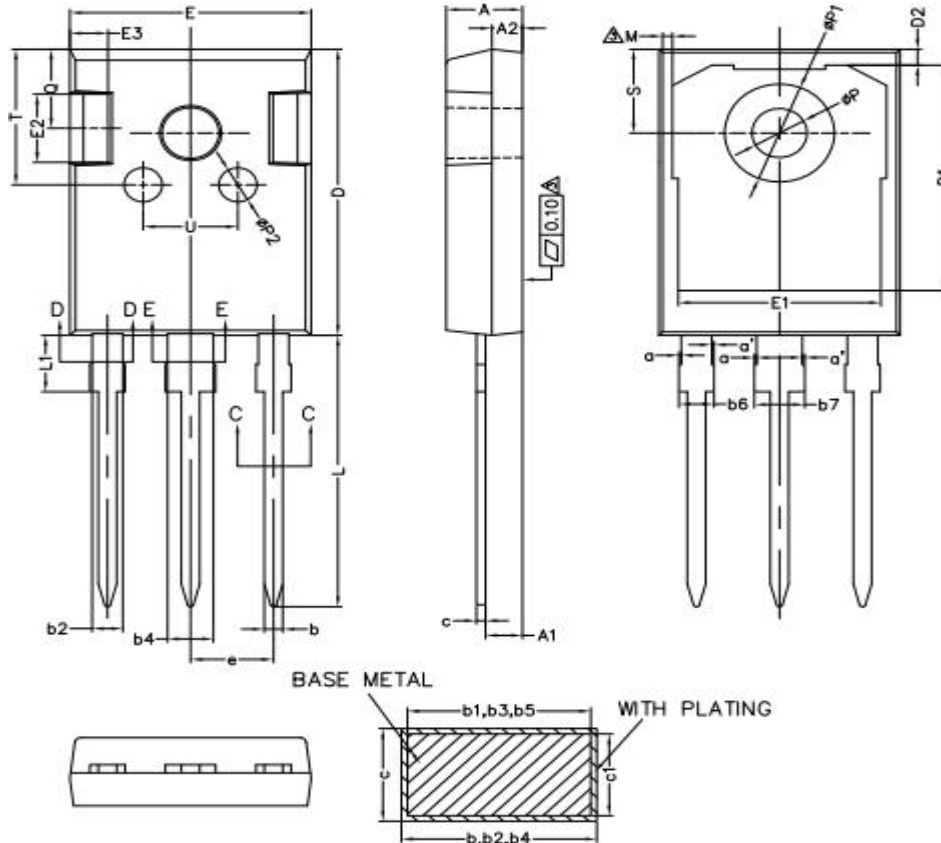


Mechanical Dimensions
TO-247(Package 1)
Unit: mm


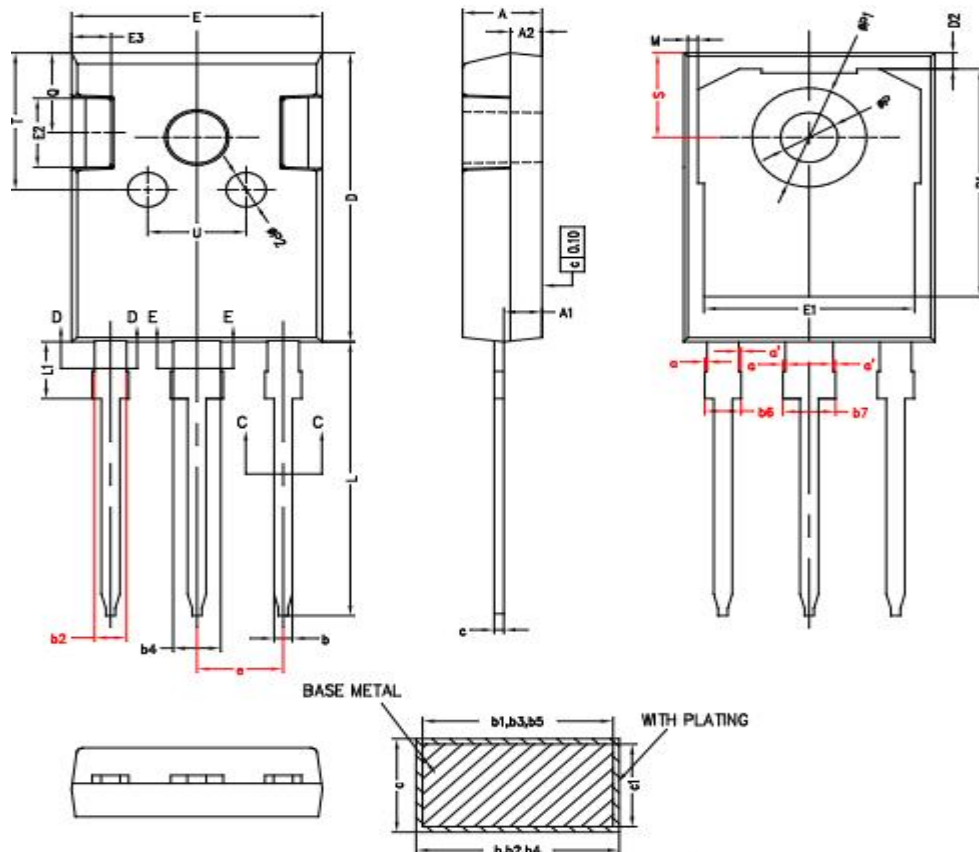
Symbol	Dimensions(mm)			Symbol	Dimensions(mm)		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.80	5.00	5.20	E1	-	13.30	-
A1	2.21	2.41	2.61	E2	-	5.00	-
A2	1.90	2.00	2.10	E3	-	2.50	-
b	1.10	1.20	1.35	L	19.42	19.92	20.42
b1	-	2.00	-	L1	-	4.13	-
b2	-	3.00	-	P	3.50	3.60	3.70
c	0.55	0.60	0.75	P1	-	7.19	-
D	20.80	21.00	21.20	P2	-	2.50	-
D1	-	16.55	-	Q	-	5.80	-
D2	-	1.20	-	S	6.05	6.15	6.25
E	15.60	15.80	16.0	T	-	10.00	-
U	-	6.20	-				

Mechanical Dimensions
TO-247(Package 2)
Unit: mm


Symbol	Dimensions(mm)			Symbol	Dimensions(mm)		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.90	5.00	5.10	E1	13.10	13.25	13.40
A1	2.31	2.41	2.51	E2	4.85	4.95	5.10
A2	1.90	2.00	2.10	E3	2.40	2.50	2.60
b	1.15	1.20	1.25	L	19.80	19.98	20.15
b1	1.95	2.10	2.25	L1	-	-	4.30
b2	2.95	3.10	3.25	ΦP	3.60	3.70	3.80
c	0.55	0.60	0.65	ΦP1	3.40	3.50	3.60
D	20.90	21.00	21.10	ΦP2	6.90	7.10	7.30
D1	16.35	16.55	16.75	Q	5.60	5.80	6.00
D2	1.05	1.20	1.35	S	6.05	6.15	6.25
E	15.70	15.80	15.90	T	9.80	10.00	10.20
U	6.00	6.20	6.40	e	5.40	5.44	5.48
Θ1	5°	7°	9°	ΦP3	2.40	2.50	2.60
Θ2	1°	3°	5°	Θ3	13°	15°	17°

Mechanical Dimensions
TO-247(Package 3)
Unit: mm


Symbol	Dimensions(mm)			Symbol	Dimensions(mm)		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.90	5.00	5.10	c1	0.58	0.60	0.62
A1	2.31	2.41	2.51	D	20.90	21.00	21.10
A2	1.90	2.00	2.10	D1	16.25	16.55	16.85
b	1.16	-	1.26	D2	1.05	1.20	1.35
b1	1.15	1.20	1.22	E	15.70	15.80	15.90
b2	1.96	-	2.06	E1	13.10	13.30	13.50
b3	1.95	2.00	2.02	E2	4.90	5.00	5.10
b4	2.96	-	3.06	E3	2.40	2.50	2.60
b5	2.95	3.00	3.02	e	5.34	5.44	5.54
b6	-	-	2.25	L	19.80	19.92	20.10
b7	-	-	3.25	L1	3.95	4.13	4.30
c	0.59	-	0.66	M	0.35	-	0.95
P	3.50	3.60	3.70	P1	7.00	-	7.40
P2	2.40	2.50	2.60	Q	5.60	-	6.00
S	6.05	6.15	6.25	T	9.80	-	10.20
U	6.00	-	6.40	a	0	-	0.15
a'	0	-	0.15				

Mechanical Dimensions
TO-247(Package 4)
Unit: mm


Symbol	Dimensions(mm)			Symbol	Dimensions(mm)		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.90	5.00	5.10	E2	4.90	5.00	5.10
A1	2.31	2.41	2.51	E3	2.40	2.50	2.60
A2	1.90	2.00	2.10	e	5.34	5.44	5.54
b	1.12	-	1.22	L	19.80	19.92	20.10
b1	1.11	1.16	1.18	L1	3.95	4.13	4.30
b2	1.96	-	2.06	P	3.50	3.60	3.70
c	0.59	-	0.66	P1	7.00	-	7.40
D	20.90	21.00	21.10	P2	2.40	2.50	2.60
D1	16.25	16.55	16.85	Q	5.60	-	6.00
D2	1.05	1.20	1.35	S	6.05	6.15	6.25
E	15.70	15.80	15.90	T	9.80	-	10.20
E1	13.10	13.30	13.50	U	6.00	-	6.40
b3	1.95	2.00	2.02	b6	-	-	2.25
b4	2.96	-	3.06	b7	-	-	3.25
b5	2.95	3.00	3.02	c1	0.58	0.60	0.62
M	0.35	-	0.95	a	0	-	0.15
a'	0	-	0.15				



Shenzhen Sanrise Technology Co., LTD
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